# Product End-of-Life Disassembly Instructions

**Product Category:** Notebooks and Tablet PCs

**Marketing Name / Model**
[List multiple models if applicable.]

- HP Pavilion 13 Laptop PC / Able / G7F

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPI products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

NOTE: Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking, please contact HP’s Sustainability Contact.

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td></td>
</tr>
<tr>
<td>Batteries, excluding Li-Ion batteries.</td>
<td>All types including standard alkaline, coin or button style batteries</td>
<td></td>
</tr>
<tr>
<td>Li-Ion batteries. Include all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, RTC coin cell, etc.)</td>
<td>Battery(ies) are attached to the product by ( \text{check all that apply with an “x” inside the “[ ]”:} ) [x] screws [     ] snaps [     ] adhesive [     ] other. Explain [     ] NOTE: Add detailed removal procedures including required tools in the sections 3.1 and 3.2.</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td></td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>DC Cable for External Power Supply</td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

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### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Screw driver</td>
<td>#0</td>
</tr>
<tr>
<td>Screw driver</td>
<td>#1</td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure:

1. Remove rubber foot of front and rear side and dis-fasten BASE screw*5
2. Remove BASE and dis-fasten battery screw*5
3. Remove battery and tear these tape
4. Dis-fasten the Speak screw*2 and pull out the connector and remove
5. Pull out the M/B side connector of FPR FFC
6. Dis-fasten the screw on Audio Board and unplug the FFC
7. Dis-fasten the Fan screw *3 and pull out the connector and remove
8. Dis-fasten the screw on SSD and remove
9. Pull out specific FFC connector (KB Membrane/USB/Back Light/TP)
10. Dis-fasten the screw *2 on USB Board and remove
11. Unplug specific connector (Antenna/DC cable/LVDS Cable)
12. Dis-fasten the screw*4 on M/B and remove
13. Dis-fasten the screws on DC BKT and hinge L/R BKT*4
14. Open the hinge BKT and Remove the DC BKT, DC Cable
15. Remove LCD bezel
16. Pull out the adhesive
17. Remove panel
18. Dis-fasten hinge screw*8
19. Remove CCD module, LVDS cable, antenna wire

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
1. Remove rubber foot of front and rear side and dis-fasten BASE screw*5

![Image of laptop bottom with screw locations marked]

2. Remove BASE and dis-fasten battery screw*5

![Image of laptop base removed]

3. Remove battery and tear these tape

![Image of laptop battery and tape]

4. Dis-fasten the Speak screw*2 and pull out the connector and remove

![Image of laptop with connector pulled out]
5. Pull out the M/B side connector of FPR FFC

6. Dis-fasten the screw on Audio Board and unplug the FFC

7. Dis-fasten the Fan screw *3 and pull out the connector and remove
8. Dis-fasten the screw on SSD and remove

9. Pull out specific FFC connector (KB Membrane/USB/Back Light/TP)

10. Dis-fasten the screw *2 on USB Board and remove
11. Unplug specific connector (Antenna/DC cable/LVDS Cable)

12. Dis-fasten the screw*4 on M/B and remove

13. Dis-fasten the screws on DC BKT and hinge L/R BKT*4
14. Open the hinge BKT and Remove the DC BKT, DC Cable

15. Remove LCD bezel

16. Pull out the adhesive
17. Remove panel

18. Dis-fasten hinge screw^10

19. Remove CCD module, LVDS cable, antenna wire
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